

Abstract

[Problem]

To provide a technique capable of improving positioning accuracy.

5 [Solution]

A semiconductor manufacturing device includes: an imaging device that includes a first camera which photographs a substrate having a tab area on which a die is placed and a reference mark, a second camera which
10 photographs the reference mark, and a lens unit; and a coaxial lighting device. The lens unit includes: a first lens which functions as an objective lens of the first camera; a second lens which functions as an objective lens of the second camera; and a beam splitter which splits reflected
15 light from a subject into the first lens and the second lens.

[Selected Drawing] FIG. 5